



*Let Performance Drive*

# CMD194

## 6-20 GHz Low Noise Amplifier

### Features

- ▶ Low noise figure
- ▶ High gain broadband performance
- ▶ Single positive supply voltage
- ▶ Small die size

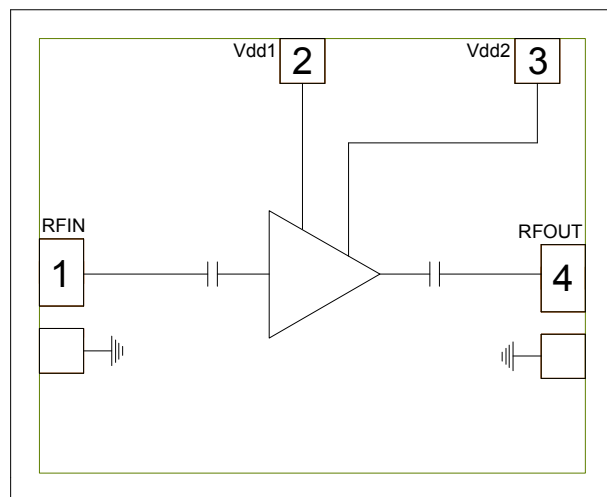
### Applications

- ▶ Point-to-point radios
- ▶ Point-to-multi-point radios
- ▶ Military EW
- ▶ Test instrumentation

### Description

The CMD194 is a broadband MMIC low noise amplifier die ideally suited for EW and communications systems where small size and low power consumption are needed. The broadband device delivers greater than 20 dB of gain with a corresponding output 1 dB compression point of +15 dBm and a noise figure of 1.75 dB. The CMD194 is a 50 ohm matched design eliminating the need for external DC blocks and RF port matching. The CMD194 offers full passivation for increased reliability and moisture protection.

### Functional Block Diagram



### Electrical Performance - $V_{dd1} = V_{dd2} = 4.0 \text{ V}$ , $T_A = 25 \text{ }^\circ\text{C}$ , $F = 13 \text{ GHz}$

| Parameter          | Min    | Typ  | Max | Units |
|--------------------|--------|------|-----|-------|
| Frequency Range    | 6 - 20 |      |     | GHz   |
| Gain               |        | 20.5 |     | dB    |
| Noise Figure       |        | 1.75 |     | dB    |
| Input Return Loss  |        | 10   |     | dB    |
| Output Return Loss |        | 17   |     | dB    |
| Output P1dB        |        | 15.5 |     | dBm   |
| Supply Current     |        | 120  |     | mA    |

ver 1.0 0216

### Specifications

#### Absolute Maximum Ratings

| Parameter                            | Rating        |
|--------------------------------------|---------------|
| Drain Voltage, V <sub>dd1, 2</sub>   | 5 V           |
| RF Input Power                       | +20 dBm       |
| Channel Temperature, T <sub>ch</sub> | 150 °C        |
| Power Dissipation, P <sub>diss</sub> | 866 mW        |
| Thermal Resistance                   | 75 °C/W       |
| Operating Temperature                | -55 to 85 °C  |
| Storage Temperature                  | -55 to 150 °C |

Operation of this device outside the maximum ratings may cause permanent damage.

#### Recommended Operating Conditions

| Parameter               | Min | Typ | Max | Units |
|-------------------------|-----|-----|-----|-------|
| V <sub>dd1, 2</sub>     | 2.0 | 4.0 | 5.0 | V     |
| I <sub>dd1 + Idd2</sub> |     | 120 |     | mA    |

Electrical performance is measured at specific test conditions. Electrical specifications are not guaranteed over all recommended operating conditions.

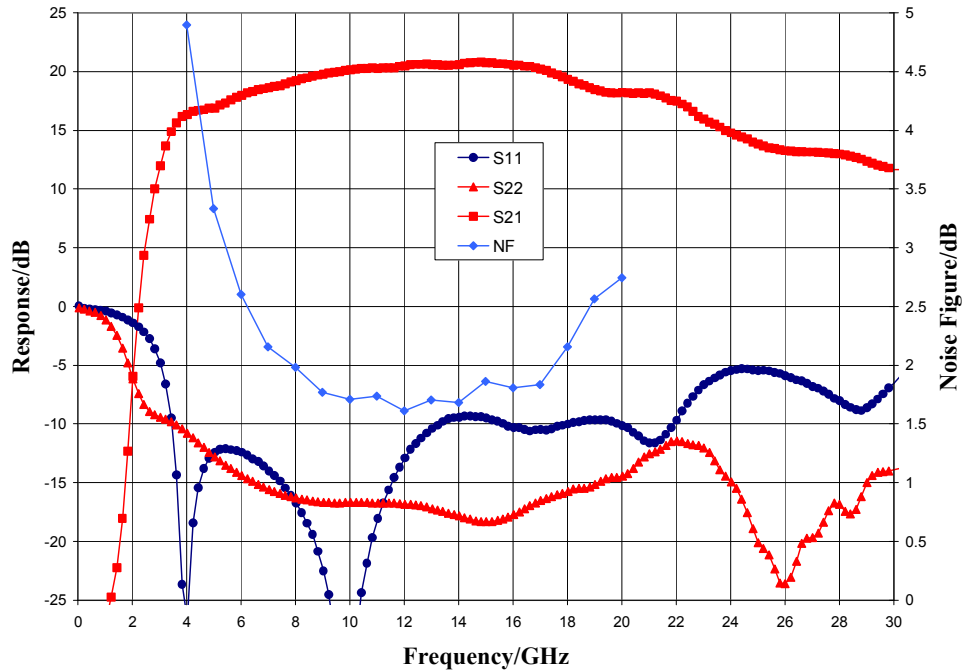
#### Electrical Specifications - V<sub>dd1</sub> = V<sub>dd2</sub> = 4.0 V, T<sub>A</sub> = 25 °C

| Parameter                            | Min    | Typ   | Max  | Min    | Typ   | Max | Units |
|--------------------------------------|--------|-------|------|--------|-------|-----|-------|
| Frequency Range                      | 6 - 20 |       |      | 9 - 17 |       |     | GHz   |
| Gain                                 | 15     | 20    | 24   | 16.5   | 20.5  | 24  | dB    |
| Noise Figure                         |        | 2     | 3.25 |        | 1.75  | 2.3 | dB    |
| Input Return Loss                    |        | 10    |      |        | 10    |     | dB    |
| Output Return Loss                   |        | 15    |      |        | 17    |     | dB    |
| Output P <sub>1dB</sub>              |        | 15    |      |        | 15    |     | dBm   |
| Output IP <sub>3</sub>               |        | 26    |      |        | 26    |     | dBm   |
| Supply Current                       | 90     | 120   | 150  | 90     | 120   | 150 | mA    |
| Gain Temperature Coefficient         |        | 0.014 |      |        | 0.014 |     | dB/°C |
| Noise Figure Temperature Coefficient |        | 0.01  |      |        | 0.01  |     | dB/°C |

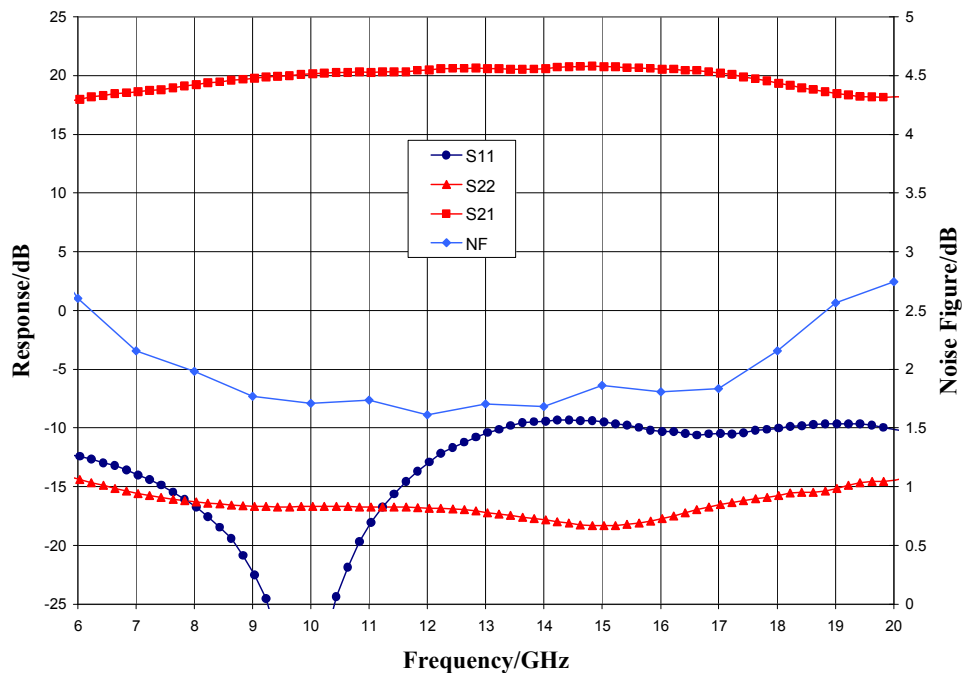
ver 1.0 0216

### Typical Performance

Broadband Performance,  $V_{dd} = 4.0 \text{ V}$ ,  $I_{dd} = 120 \text{ mA}$ ,  $T_A = 25 \text{ }^\circ\text{C}$



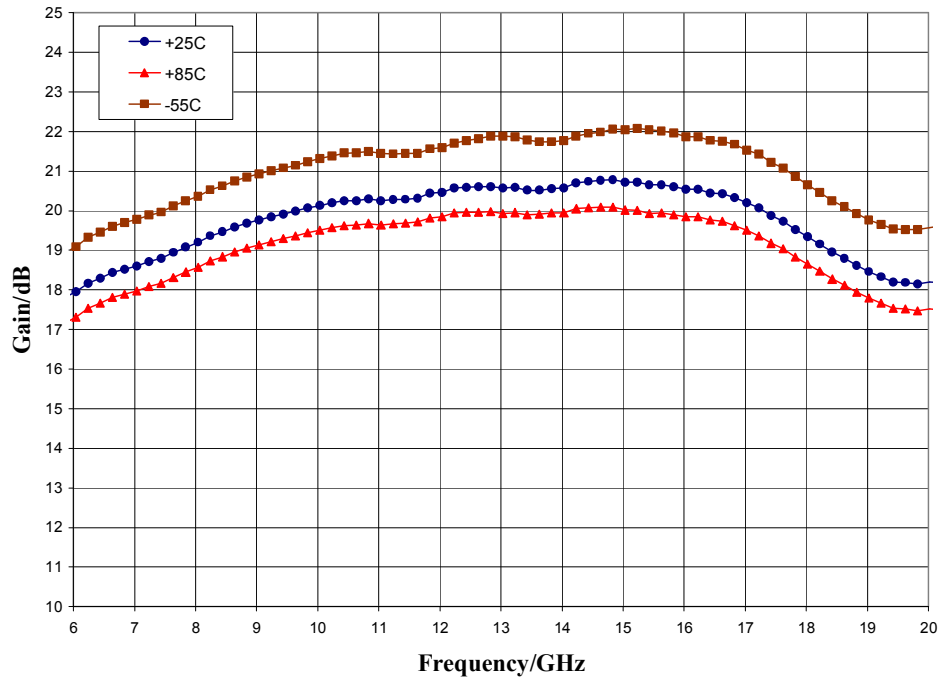
Narrow-band Performance,  $V_{dd} = 4.0 \text{ V}$ ,  $I_{dd} = 120 \text{ mA}$ ,  $T_A = 25 \text{ }^\circ\text{C}$



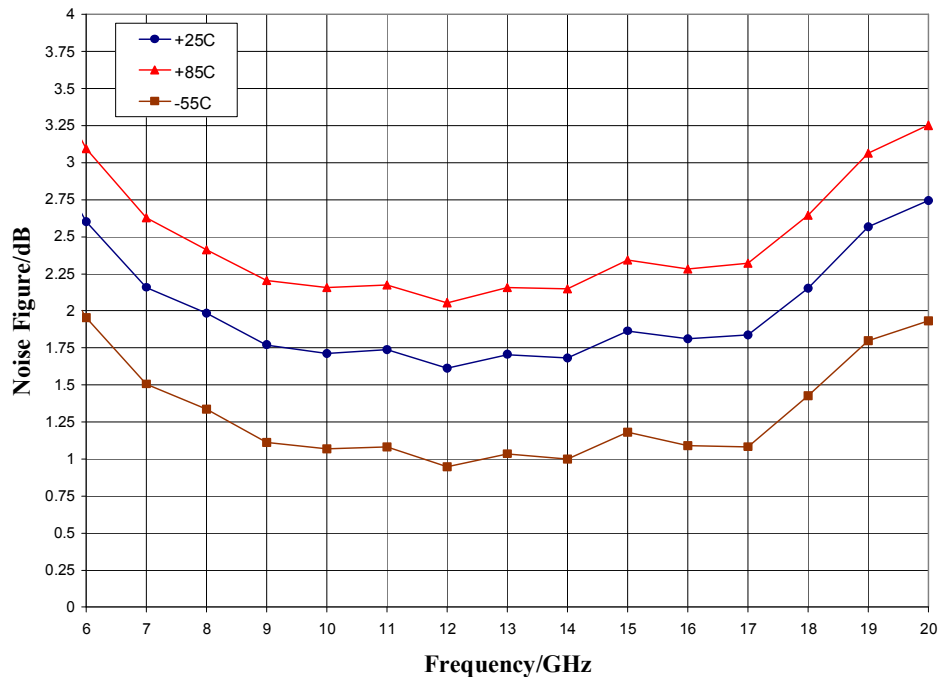
ver 1.0 0216

### Typical Performance

Gain vs. Temperature,  $V_{dd} = 4.0\text{ V}$



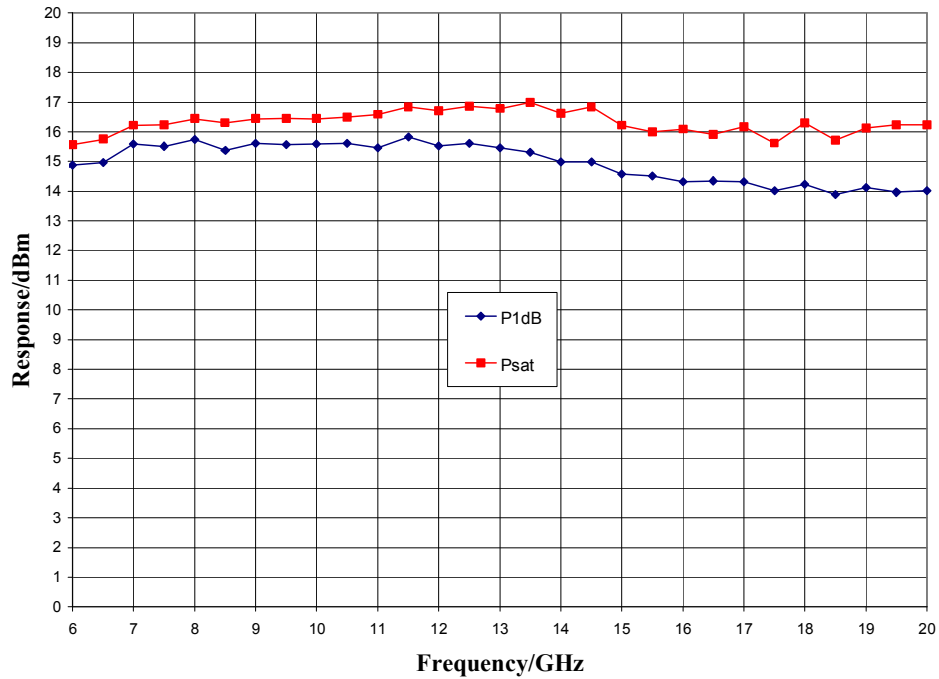
Noise Figure vs. Temperature,  $V_{dd} = 4.0\text{ V}$



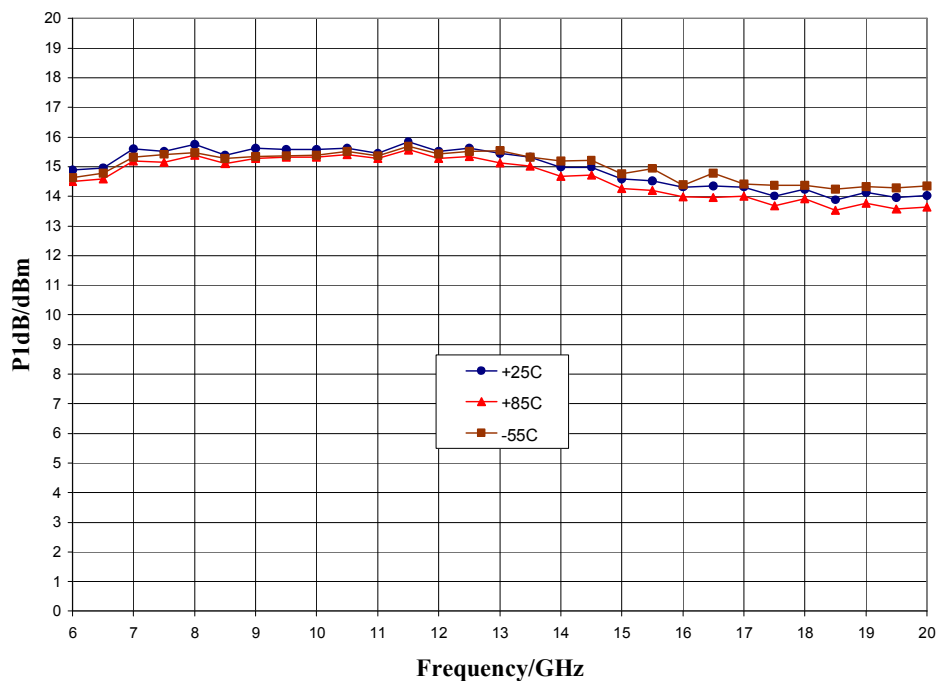
ver 1.0 0216

### Typical Performance

Output Power,  $V_{dd} = 4.0\text{ V}$ ,  $I_{dd} = 120\text{ mA}$ ,  $T_A = 25\text{ }^\circ\text{C}$



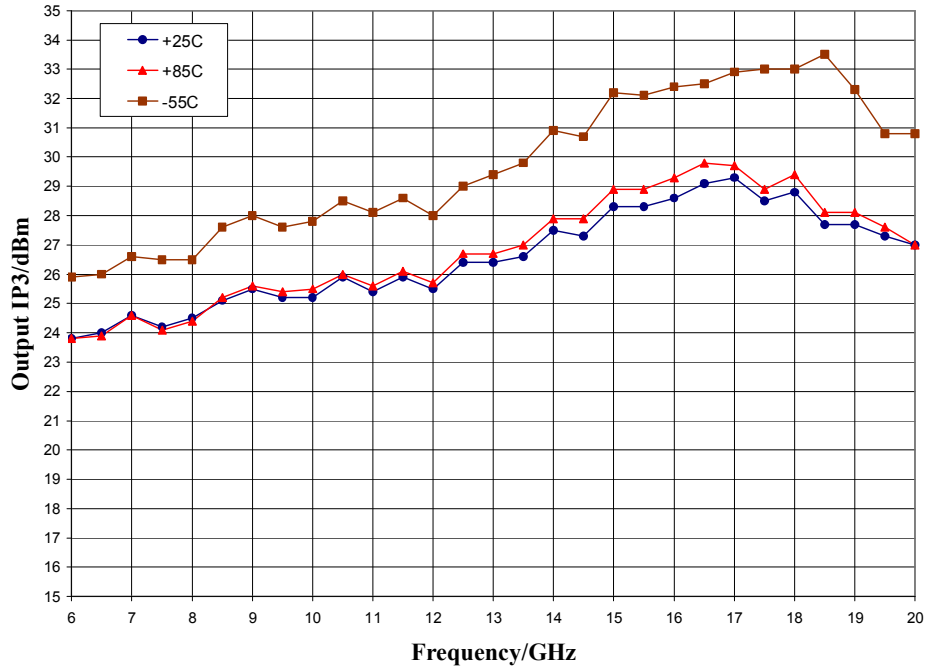
P1dB vs. Temperature,  $V_{dd} = 4.0\text{ V}$



ver 1.0 0216

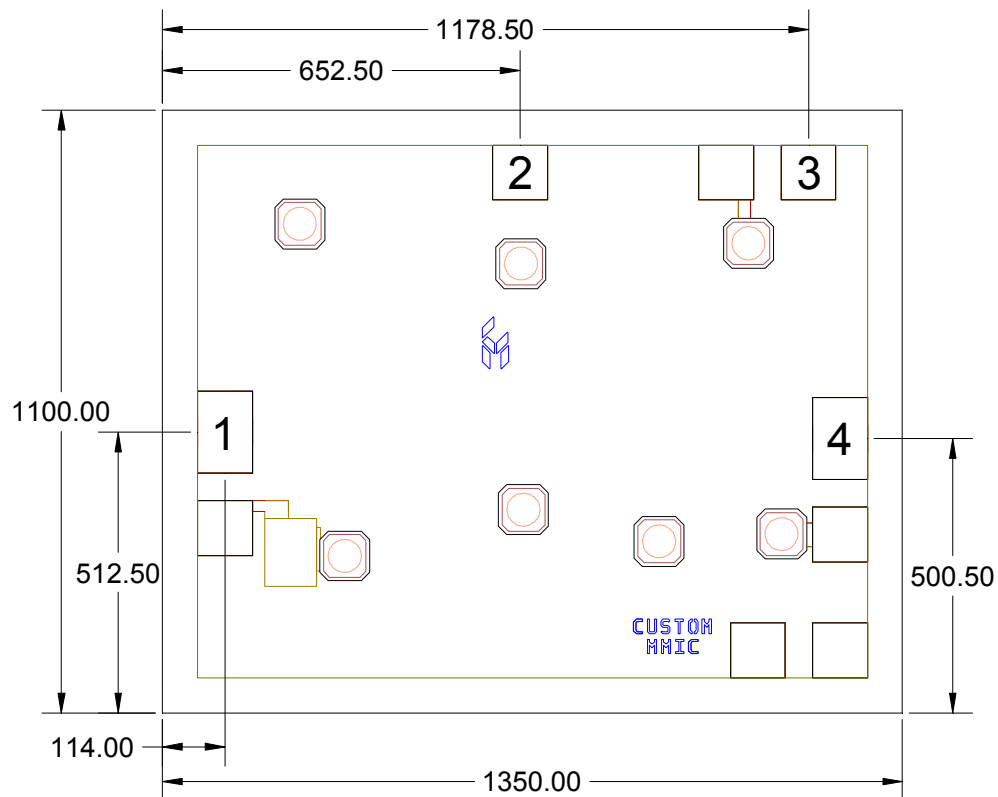
### Typical Performance

#### Output IP3 vs. Temperature, Vdd=4.0V



### Mechanical Information

#### Die Outline (all dimensions in microns)

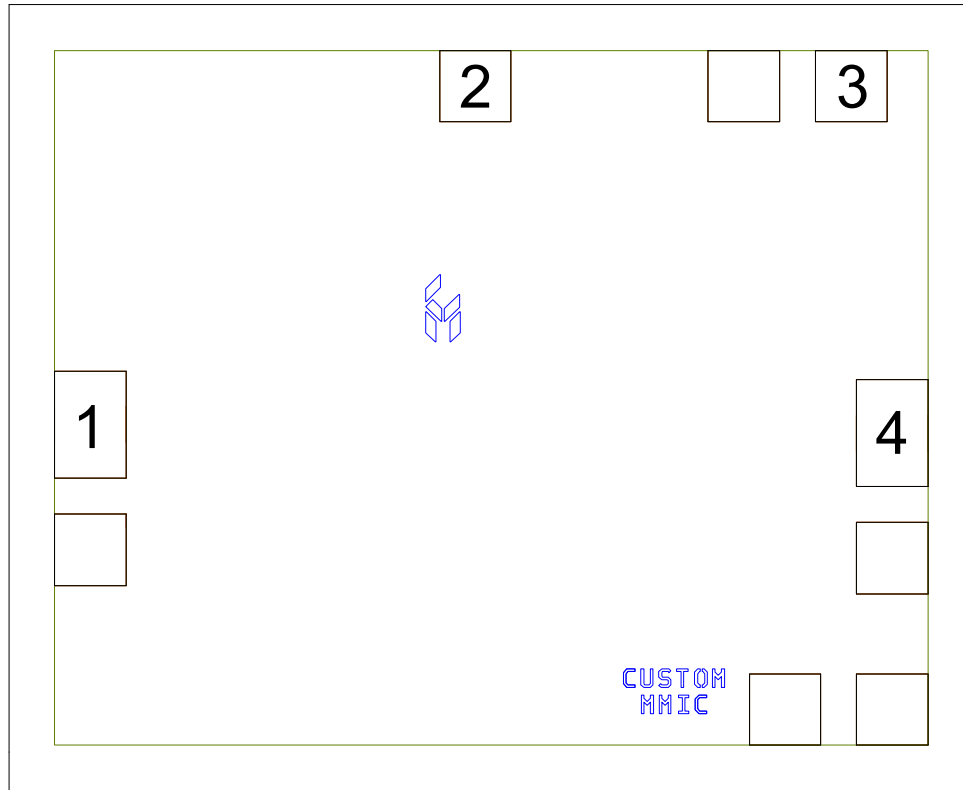


#### Notes:

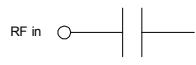
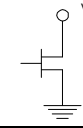


1. No connection required for unlabeled pads
2. Backside is RF and DC ground
3. Backside and bond pad metal: Gold
4. Die is 85 microns thick
5. DC bond pads are 100 microns square
6. RF bond pads are 100 x 150 microns

### Pin Description

#### Pad Diagram



#### Functional Description

| Pad      | Function | Description   | Schematic   |
|----------|----------|---|---|
| 1        | RF in    | DC blocked and 50 ohm matched                               |  |
| 2, 3     | Vdd1, 2  | Power supply voltage<br>Decoupling and bypass caps required |  |
| 4        | RF out   | DC blocked and 50 ohm matched                               |  |
| Backside | Ground   | Connect to RF / DC ground                                   |  |

ver 1.0 0216



### Applications Information

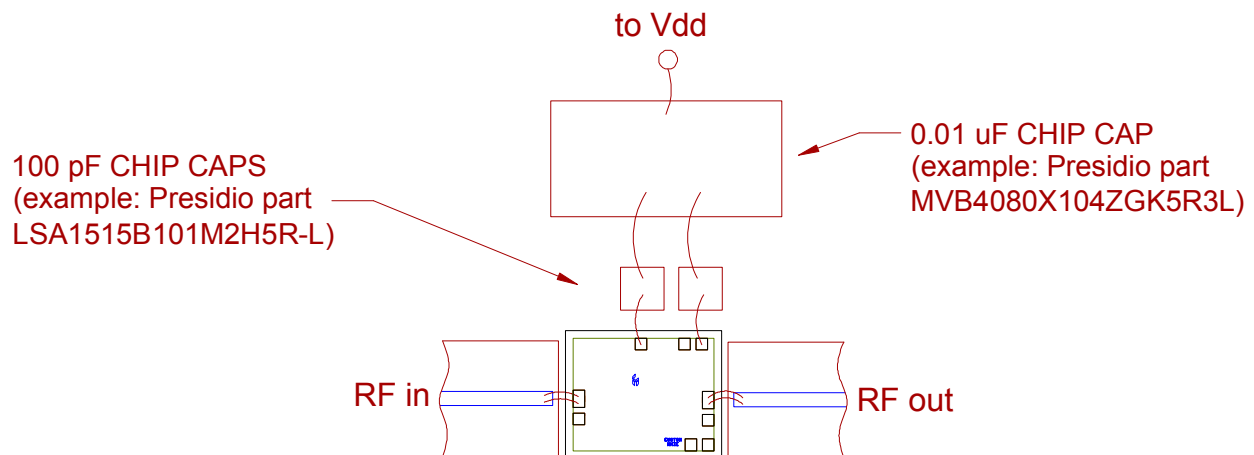
#### Assembly Guidelines

The backside of the CMD194 is RF ground. Die attach should be accomplished with electrically and thermally conductive epoxy only. Eutectic attach is not recommended. Standard assembly procedures should be followed for high frequency devices. The top surface of the semiconductor should be made planar to the adjacent RF transmission lines, and the RF decoupling capacitors placed in close proximity to the DC connections on chip.

RF connections should be made as short as possible to reduce the inductive effect of the bond wire. Use of a 0.8 mil thermosonic wedge bonding is highly recommended as the loop height will be minimized. The RF input and output require a double bond wire as shown.

The semiconductor is 85  $\mu\text{m}$  thick and should be handled by the sides of the die or with a custom collet. Do not make contact directly with the die surface as this will damage the monolithic circuitry. Handle with care.

#### Assembly Diagram



**GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.**

ver 1.0 0216

### *Applications Information*

#### **Biasing and Operation**

The CMD194 is biased with a positive drain supply. Performance is optimized when the drain voltage is set to +4.0 V.

Turn ON procedure:

1. Apply drain voltage  $V_{dd1}$ ,  $V_{dd2}$  and set to +4 V

Turn OFF procedure:

1. Turn off drain voltage  $V_{dd1}$ ,  $V_{dd2}$

RF power can be applied at any time.